PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Mail Stop PCT

Intl.

Appl. No.: PCT/JP2004/004886

Applicant : Eiji KAMIYAMA et al.

Intl. Appl.

Filed : April 2, 2004

TC/A.U. : Not Assigned

Examiner : Not Assigned

Dkt. No. : ABE-034

Cust. No.: 20374

UNDER 37 C.F.R. §1.97(b)

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

September 27, 2005

Sir:

The attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached Form PTO-1449. One copy of each document is attached.

No fee or statement is required in connection with this Information Disclosure Statement, since it is being submitted prior to the last of (1) issuance of a first official action on the merits and (2) expiration of the three month period following filing of the above-captioned application.

Documents UA to UE, DA and DB are in the English language. Therefore, no concise explanation of the relevance of the documents is believed to be required under 37 C.F.R. §1.98.

Documents FA to FC are not in the English language. However, the concise explanation of the relevance of the documents required under 37 C.F.R. §1.98 is believed to be satisfied by the submission of English language abstracts thereof. Please note that documents UA to UC are corresponding English language publications of documents FA to FC, respectively.

Documents FD and FE are also not in the English language. However, the concise explanation of the relevance of the documents required under 37 C.F.R. \$1.98 is believed to be satisfied by the submission of English language abstracts and translations thereof.

Documents FA to FE have been cited in the International Search Report of the present application. A copy of the search report is being filed concurrently herewith. The relevance of each document is also discussed in the International Search report. Please note an Examiner's obligation to consider documents cited in an International Search Report according to the provisions of MPEP \$1893.03(g).

Documents UD and UE are described in the paragraph beginning

U.S. National Stage of PCT/JP2004/004886 INFORMATION DISCLOSURE STATEMENT

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on page 2, line 20. Document DB is described in the paragraph beginning on page 3, line 5. Document FC is described in the paragraph beginning on page 3, line 16.

The Commissioner is authorized to charge our Deposit Account No. 111833 for any fee which is deemed by the Patent and Trademark Office to be required to effect consideration of this statement.

Respectfully submitted,

KUBOVCIK & KUBOVCIK

Keiko Tanaka Kubovcik

Reg. No. 40,428

Atty. Case No. ABE-034
The Farragut Building
Suite 710
900 17th Street, N.W.
Washington, D.C. 20006
Tel: (202) 887-9023

Fax: (202) 887-9093

KTK/jbf

Attachments: PTO-1449

Twelve Documents

JC12 Rec'd PCT/PTC 27 SEP 2005

				Atty. Docket No. ABE-034 Atty. Docket No. ABE-034 Atty. Docket No. ABE-034					
INFORMATION DISCLOSURE STATEMENT					ABE-034		101	Not assigned	
PTO-1449					Applicant: Eiji KAMIYAMA et al.				
					Filing Date: September 27, 2005		Group: Not assigned		
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	DB	Tong, Q.Y. et al., "SemiConductor Wafer Bonding: Science and Technology"; November, 1998:printout of website http://www3.interscience.wiley.com:8100/WileyCDA/WileyTitle/productCd-0471574813,desc Cd-description.html?print=true.							
	DC								
Examiner: Date Considered:									

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